

BUK962R8-60E-VB Datasheet

N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY	
V_{DS} (V)	60
$R_{DS(on)}$ (Ω) at $V_{GS} = 10$ V	0.0028
$R_{DS(on)}$ (Ω) at $V_{GS} = 4.5$ V	0.0120
I_D (A)	210
Configuration	Single

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- Package with Low Thermal Resistance
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT
HALOGEN
FREE



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V_{DS}	60	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current	$T_C = 25$ °C	I_D	210	A
	$T_C = 125$ °C		120 ^a	
Continuous Source Current (Diode Conduction) ^a		I_S	120 ^a	
Pulsed Drain Current ^b		I_{DM}	480	
Single Pulse Avalanche Current	L = 0.1 mH	I_{AS}	75	
Single Pulse Avalanche Energy		E_{AS}	281	mJ
Maximum Power Dissipation ^b	$T_C = 25$ °C	P_D	375	W
	$T_C = 125$ °C		125	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to + 175	°C

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount ^c	R_{thJA}	40	°C/W
Junction-to-Case (Drain)		R_{thJC}	0.4	

Notes

- Package limited.
- Pulse test; pulse width ≤ 300 μ s, duty cycle ≤ 2 %.
- When mounted on 1" square PCB (FR-4 material).
- Parametric verification ongoing.

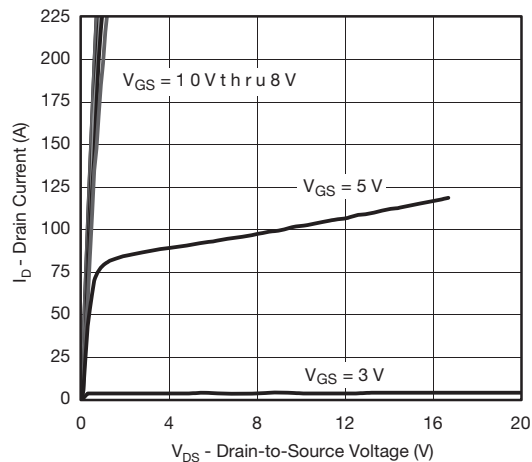
SPECIFICATIONS (T _C = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0, I _D = 250 μA		60	-	-	V
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		2.0		4.0	
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V	V _{DS} = 60 V	-	-	1.0	μA
		V _{GS} = 0 V	V _{DS} = 60 V, T _J = 125 °C	-	-	50	
		V _{GS} = 0 V	V _{DS} = 60 V, T _J = 175 °C	-	-	350	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	V _{DS} ≥ 5 V	120	-	-	A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 30 A	-	0.0028	-	Ω
		V _{GS} = 10 V	I _D = 30 A, T _J = 125 °C	-	0.0060	-	
		V _{GS} = 10 V	I _D = 30 A, T _J = 175 °C	-	0.0080	-	
		V _{GS} = 4.5 V	I _D = 20 A	-	0.012	-	
Forward Transconductance ^b	g _{fs}	V _{DS} = 15 V, I _D = 30 A		-	109	-	S
Dynamic ^b							
Input Capacitance	C _{iss}	V _{GS} = 0 V	V _{DS} = 25 V, f = 1 MHz	-	7300	9125	pF
Output Capacitance	C _{oss}			-	935	1170	
Reverse Transfer Capacitance	C _{rss}			-	647	810	
Total Gate Charge ^c	Q _g	V _{GS} = 10 V	V _{DS} = 30 V, I _D = 110 A	-	184	276	nC
Gate-Source Charge ^c	Q _{gs}			-	24.7	-	
Gate-Drain Charge ^c	Q _{gd}			-	50.4	-	
Gate Resistance	R _g	f = 1 MHz		0.5	1.1	1.6	Ω
Turn-On Delay Time ^c	t _{d(on)}	V _{DD} = 30 V, R _L = 0.27 Ω I _D ≅ 110 A, V _{GEN} = 10 V, R _g = 2.5 Ω		-	19	29	ns
Rise Time ^c	t _r			-	23	35	
Turn-Off Delay Time ^c	t _{d(off)}			-	83	125	
Fall Time ^c	t _f			-	35	53	
Source-Drain Diode Ratings and Characteristics ^b							
Pulsed Current ^a	I _{SM}			-	-	480	A
Forward Voltage	V _{SD}	I _F = 100 A, V _{GS} = 0		-	0.9	1.5	V

Notes

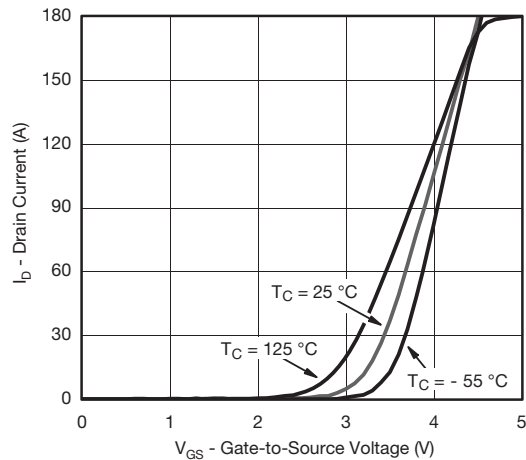
- Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
- Guaranteed by design, not subject to production testing.
- Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

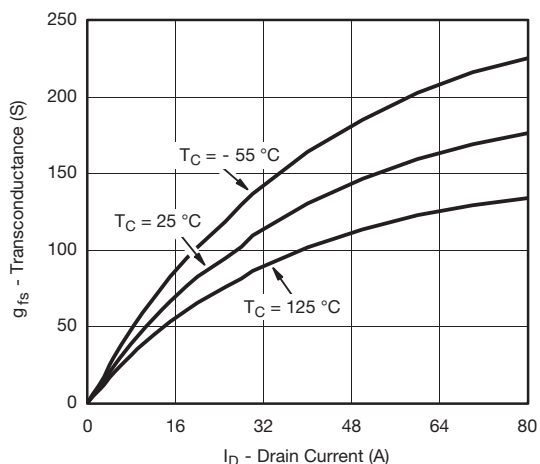
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



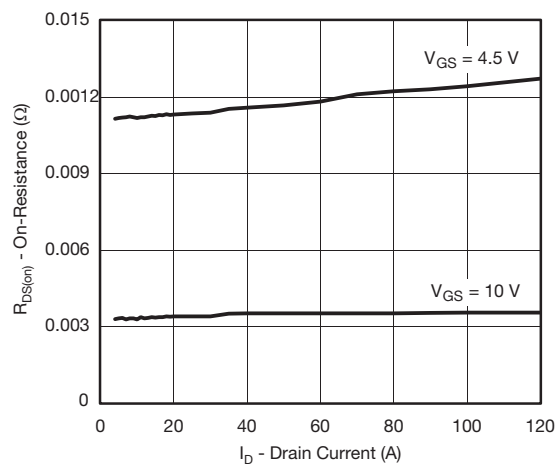
Output Characteristics



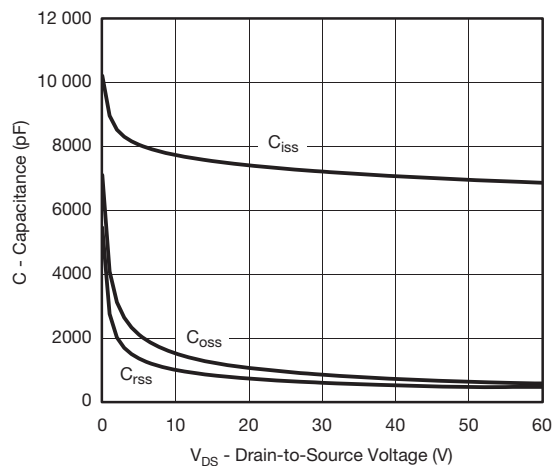
Transfer Characteristics



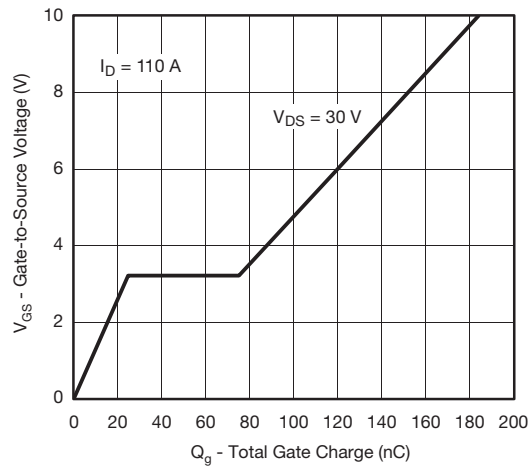
Transconductance



On-Resistance vs. Drain Current



Capacitance

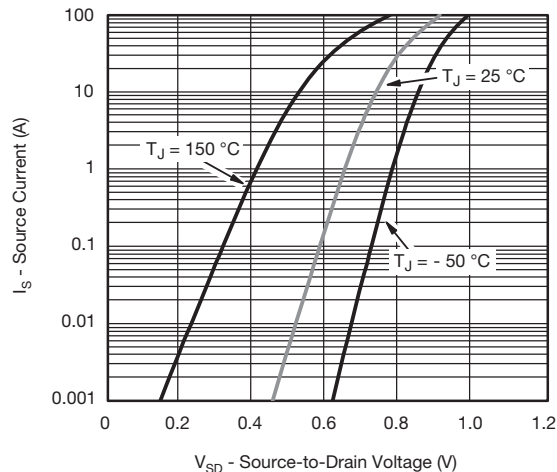


Gate Charge

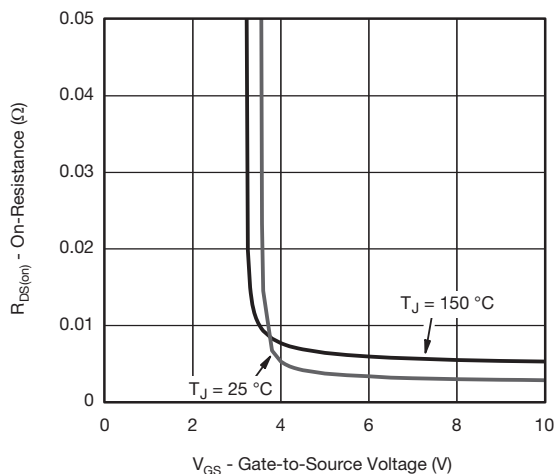
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



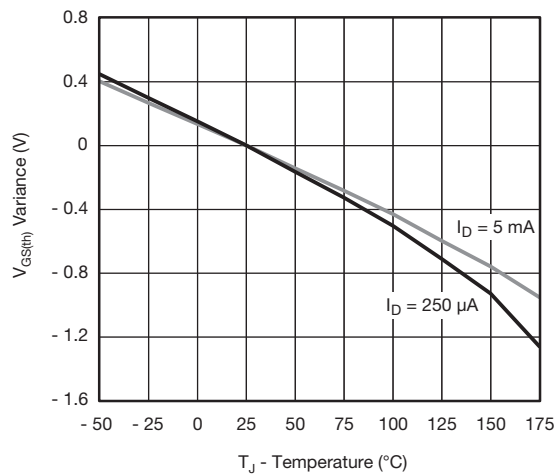
On-Resistance vs. Junction Temperature



Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Drain Source Breakdown vs. Junction Temperature

THERMAL RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

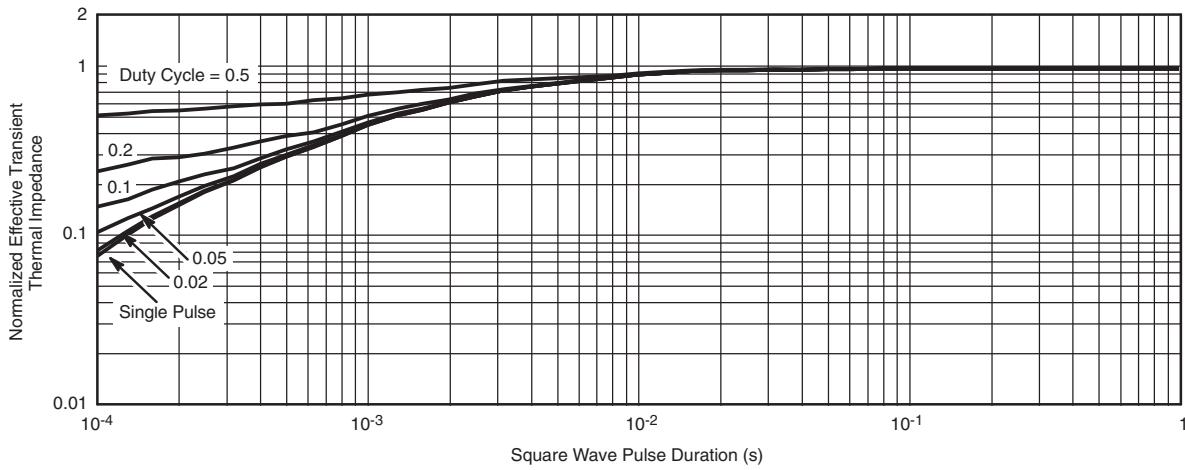


Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient

THERMAL RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient ($25\text{ }^{\circ}\text{C}$)
 - Normalized Transient Thermal Impedance Junction-to-Case ($25\text{ }^{\circ}\text{C}$)
 are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Technical drawing of a probe tip assembly, showing front, side, and detail views with dimensions and GD&T features.

Front View: Shows the probe tip with dimensions E , D , H , $L1$, $L2$, $L3$, $L4$, $b1$, $b2$, $b3$, $c1$, $c2$, c , A , B , C , $D1$, $E1$, F , G , H , I , J , K , L , M , N , O , P , Q , R , S , T , U , V , W , X , Y , Z . GD&T features include Datum A, Feature Control Frames for $\phi 0.010 \text{ M} \text{ A} \text{ B}$, Plating , Base metal , Lead tip , and Seating plane .

Side View: Shows the side profile of the probe tip with dimensions E , D , H , $L1$, $L2$, $L3$, $L4$, $b1$, $b2$, $b3$, $c1$, $c2$, c , A , B , C , $D1$, $E1$, F , G , H , I , J , K , L , M , N , O , P , Q , R , S , T , U , V , W , X , Y , Z . GD&T features include Datum A, Feature Control Frames for Plating , Base metal , Lead tip , and Seating plane .

Detail A: Shows a magnified view of the probe tip with dimensions E , D , H , $L1$, $L2$, $L3$, $L4$, $b1$, $b2$, $b3$, $c1$, $c2$, c , A , B , C , $D1$, $E1$, F , G , H , I , J , K , L , M , N , O , P , Q , R , S , T , U , V , W , X , Y , Z . GD&T features include Datum A, Feature Control Frames for Plating , Base metal , Lead tip , and Seating plane .

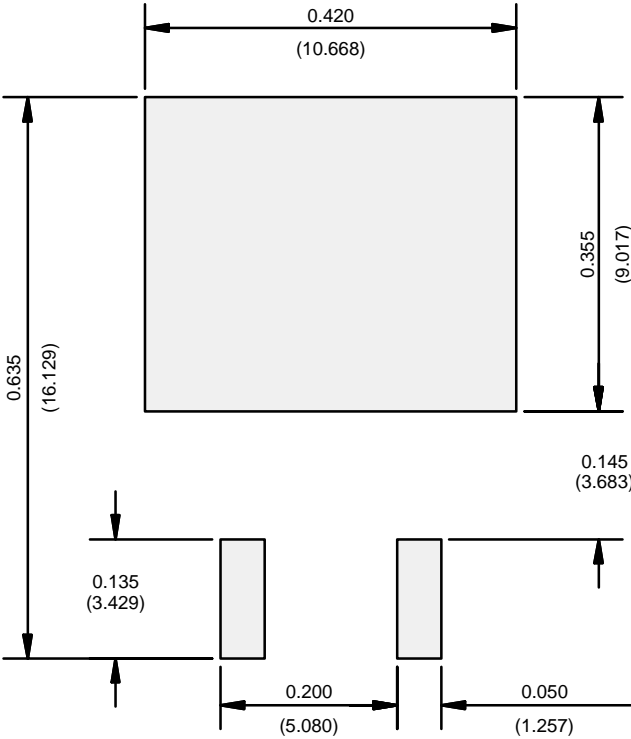
Section B - B and C - C: Shows cross-sections of the probe tip with dimensions E , D , H , $L1$, $L2$, $L3$, $L4$, $b1$, $b2$, $b3$, $c1$, $c2$, c , A , B , C , $D1$, $E1$, F , G , H , I , J , K , L , M , N , O , P , Q , R , S , T , U , V , W , X , Y , Z . GD&T features include Datum A, Feature Control Frames for Plating , Base metal , Lead tip , and Seating plane .

View A - A: Shows the probe tip from a different perspective with dimensions E , D , H , $L1$, $L2$, $L3$, $L4$, $b1$, $b2$, $b3$, $c1$, $c2$, c , A , B , C , $D1$, $E1$, F , G , H , I , J , K , L , M , N , O , P , Q , R , S , T , U , V , W , X , Y , Z . GD&T features include Datum A, Feature Control Frames for Plating , Base metal , Lead tip , and Seating plane .

	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	-
e	2.54 BSC		0.100 BSC	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	-	0.066
L2	-	1.78	-	0.070
L3	0.25 BSC		0.010 BSC	
L4	4.78	5.28	0.188	0.208

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
5. Dimension b1 and c1 apply to base metal only.
6. Datum A and B to be determined at datum plane H.
7. Outline conforms to JEDEC outline to TO-263AB.

RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads
Dimensions in Inches/(mm)

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